N-Channel 150 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (mΩ)(Typ.)	I _D (A)		
150	98 at V _{GS} = 10 V	30		
	110 at V _{GS} = 4.5 V] 30		

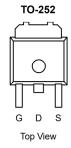
FEATURES

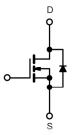
- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- 100 % R_g and UIS tested



APPLICATIONS

· Primary Side Switch





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C =$	25 °C, unless other	rwise noted)		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	150	
Gate-Source Voltage		V _{GS}	± 20	\ \ \
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 25 °C		30	
	T _C = 125 °C	- I _D -	19	1
Pulsed Drain Current		I _{DM}	90	А
Continuous Source Current (Diode Conduction)		I _S	30	
Avalanche Current		I _{AR}	25	1
Repetitive Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AR}	70	mJ
Maximum Power Dissipation	T _C = 25 °C	P _D	93 ^b	w
	T _A = 25 °C		2.9 ^a] vv
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient ^a	t ≤ 10 s	- R _{thJA}	16	20	°C/W
Junction-to-Ambient*	Steady State		45	55	
Junction-to-Case		R _{thJC}	2	2.4	

- a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.

Rev.C 1



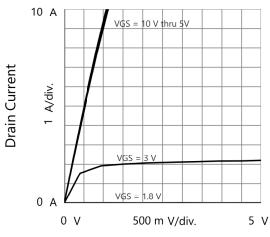
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	150			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		3		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		V _{DS} = 150 V, V _{GS} = 0 V	1		1		
	I _{DSS}	V _{DS} = 120 V, V _{GS} = 0 V, T _J = 125 °C			50	μA	
		V _{DS} = 120 V, V _{GS} = 0 V, T _J = 175 °C			250	1	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	30			Α	
		V _{GS} = 10 V, I _D = 10 A		98	115		
		V _{GS} = 10 V, I _D = 10 A, T _J = 125 °C		105	123		
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A, T _J = 175 °C		120	145	$m\Omega$	
		V _{GS} = 4.5 V, I _D = 8 A		110	132		
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 10 A		25		S	
Dynamic ^a							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 75 V, f = 1 MHz		955		pF	
Output Capacitance	C _{oss}			41			
Reverse Transfer Capacitance	C _{rss}			30			
Total Gate Charge ^c	Qg			26			
Gate-Source Charge ^c	Q _{gs}	V _{DS} = 75 V, V _{GS} = 10 V, I _D = 10 A		2		nC	
Gate-Drain Charge ^c	Q _{gd}			19			
Gate Resistance	R _g	V _{GS} = 0 V, f = 1 MHz		9		Ω	
Turn-On Delay Time ^c	t _{d(on)}			8		ns ns	
Rise Time ^c	t _r	$V_{DD} = 75 \text{ V}, R_L = 5 \Omega$ $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.5 \Omega$		35			
Turn-Off Delay Time ^c	t _{d(off)}			17			
Fall Time ^c	t _f			30			
Source-Drain Diode Ratings and Cha	racteristic (T	C = 25 °C)					
Pulsed Current	I _{SM}				90	Α	
Diode Forward Voltage ^b	V _{SD}	I _F = 10 A, V _{GS} = 0 V		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 10 A, dI/dt = 100 A/μs		55		ns	

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width $\leq 300 \ \mu s$, duty cycle $\leq 2 \ \%$.
- c. Independent of operating temperature.

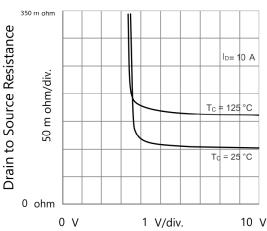
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



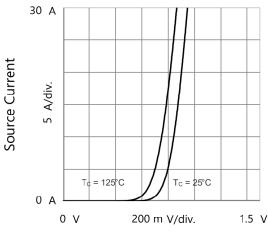
TYPICAL CHARACTERISTICS (25 °C unless noted)



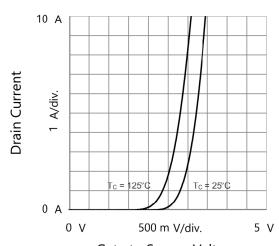
Drain to Source Voltage **Output Characteristics**



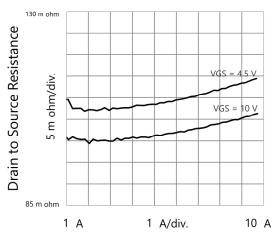
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltage



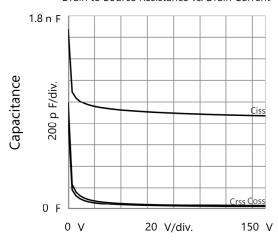
Source to Drain Voltage Body Diode Forward Characteristics



Gate to Source Voltage Transfer Characteristics



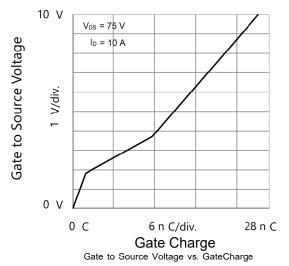
Drain Current
Drain to Source Resistance vs. Drain Current

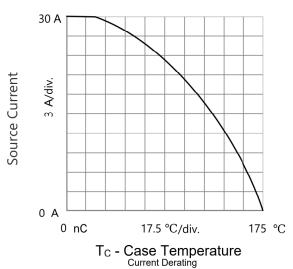


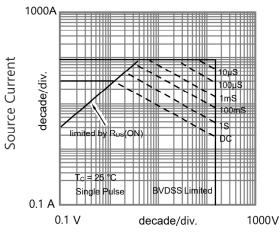
Drain to Source Voltage Capacitances



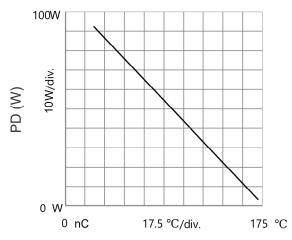
TYPICAL CHARACTERISTICS (25 °C unless noted)



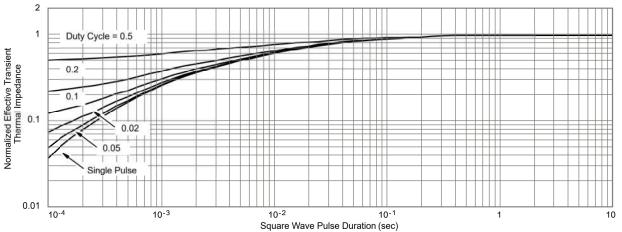




Source to Drain Voltage Safe Operating Area, Junction-to-Ambient



T_C - Case Temperature Power Derating



Normalized Thermal Transient Impedance, Junction-to-Case



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